

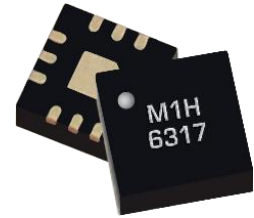
GaAs MMIC Double Balanced Mixer

MM1-1040HPSM

1. Device Overview

1.1 General Description

The MM1-1040HPSM is a GaAs MMIC double balanced mixer suitable for both up and down-conversion applications. As with all Marki Microwave mixers, it features excellent conversion loss, isolation and spurious performance across a broad bandwidth and in a small form factor. The MM1-1040HPSM is available in a lead-free, RoHS compliant 3x3 mm QFN package and is compatible with standard leaded and lead-free PCB reflow soldering processes. Evaluation boards are also available. For a list of recommended LO driver amps for all mixers and IQ mixers, see [here](#).



3x3 mm
plastic QFN

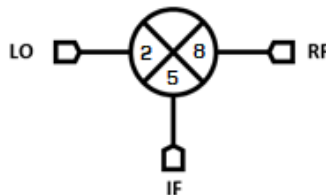
1.2 Features

Parameter	Typical
RF/LO response	10GHz – 40 GHz
IF response	DC – 12 GHz
Conversion Loss	7 dB
LO to RF Isolation	45 dB

1.3 Applications

- Test and measurement equipment
- Electronic Warfare
- 5G
- SATCOM

1.4 Functional Block Diagram



1.5 Part Ordering Options¹

Part Number	Description	Package	Green Status	Product Lifecycle	Export Classification
MM1-1040HPSM-2	3x3 mm QFN	PSM	RoHS	Active	EAR99
EVAL-MM1-1040HP	Connectorized Evaluation Fixture	Eval	Non-RoHS	Active	EAR99

¹ Refer to our [website](#) for a list of definitions for terminology presented in this table.

Table of Contents

1. Device Overview	1	3.5 Electrical Specifications	5
1.1 General Description.....	1	3.6 Typical Performance Plots	6
1.2 Features	1	3.6.1 Typical Performance Plots: IP3 ..	8
1.3 Applications	1	3.6.2 Typical Performance Plots: LO	
1.4 Functional Block Diagram	1	Harmonic Isolation.....	9
1.5 Part Ordering Options.....	1	3.6.3 Typical Spurious Performance:	
2. Port Configurations and Functions	3	Down-Conversion	10
2.1 Port Diagram	3	3.6.4 Typical Spurious Performance: Up-	
2.2 Port Functions	3	Conversion	10
3. Specifications	4	4. Operation.....	11
3.1 Absolute Maximum Ratings.....	4	4.1 Ports Operation	11
3.2 Package Information	4	5. Mechanical Data	12
3.3 Recommended Operating Conditions .	4	5.1 SM Package Outline Drawing	12
3.4 Sequencing Requirements	4	5.2 SM Package Footprint	12
		5.3 Evaluation Board Outline Drawing...	13

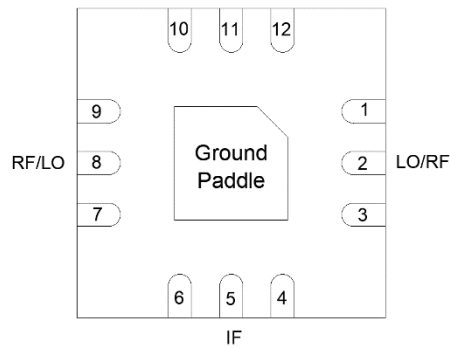
Revision History

Revision Code	Revision Date	Comment
-	June 2021	Datasheet Initial Release


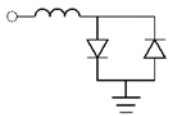


2. Port Configurations and Functions

2.1 Port Diagram

A bottom-up view of the MM1-1040HPSM's PSM package outline drawing is shown below. The MM1-1040HPSM has the input and output ports given in Port Functions. The MM1-1040HPSM can be used in either an up or down conversion application. For configuration A, input the LO into pin 2, use pin 8 for the RF, and pin 5 for the IF. For configuration B, input the LO into pin 8, use pin 2 for the RF, and pin 5 for the IF.



2.2 Port Functions

Port	Function	Description	Equivalent Circuit for Package
Pin 2	LO (Configuration A) RF (Configuration B)	Pin 2 is DC short and AC matched to 50 Ohms from 10 to 40 GHz.	
Pin 5	IF	Pin 5 is DC coupled to the diodes. Blocking capacitor is optional.	
Pin 8	RF (Configuration A) LO (Configuration B)	Pin 8 is DC open and AC matched to 50 Ohms from 10 to 40 GHz.	
GND	Ground	PSM package ground path is provided through the ground paddle.	GND 

3. Specifications

3.1 Absolute Maximum Ratings

The Absolute Maximum Ratings indicate limits beyond which damage may occur to the device. If these limits are exceeded, the device may be inoperable or have a reduced lifetime.

Parameter	Maximum Rating	Units
Pin 2 DC Current	15	mA
Pin 5 DC Current	24	mA
Pin 8 DC Current	N/A	mA
Power Handling, at any Port	+25 at +25°C, derated linearly to +21 dBm at +100°C	dBm
Operating Temperature	-55 to +100	°C
Storage Temperature	-65 to +125	°C

3.2 Package Information

Parameter	Details	Rating
ESD	Human Body Model (HBM), per MIL-STD-750, Method 1020	1A
Weight	EVAL package	11.4 g

3.3 Recommended Operating Conditions

The Recommended Operating Conditions indicate the limits, inside which the device should be operated, to guarantee the performance given in Electrical Specifications. Operating outside these limits may not necessarily cause damage to the device, but the performance may degrade outside the limits of the electrical specifications. For limits, above which damage may occur, see Absolute Maximum Ratings.

	Min	Nominal	Max	Units
T _A , Ambient Temperature	-55	+25	+100	°C
LO Input Power	+12	+17	+20	dBm

3.4 Sequencing Requirements

There is no requirement to apply power to the ports in a specific order. However, it is recommended to provide a 50Ω termination to each port before applying power. This is a passive diode mixer that requires no DC bias.

3.5 Electrical Specifications

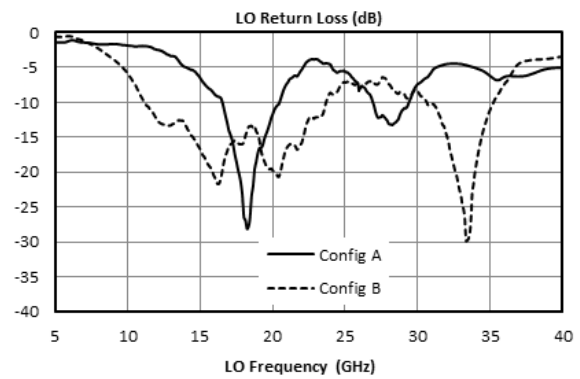
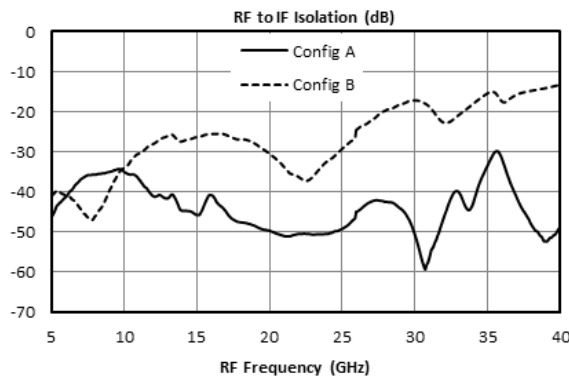
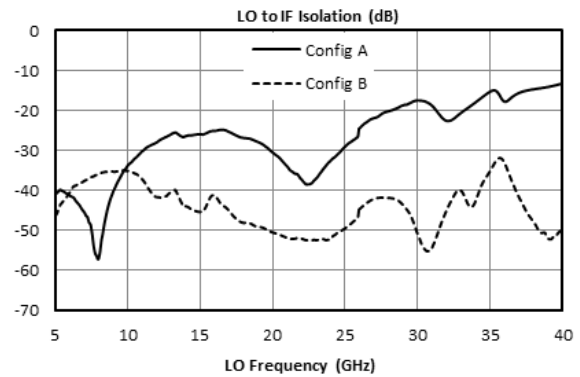
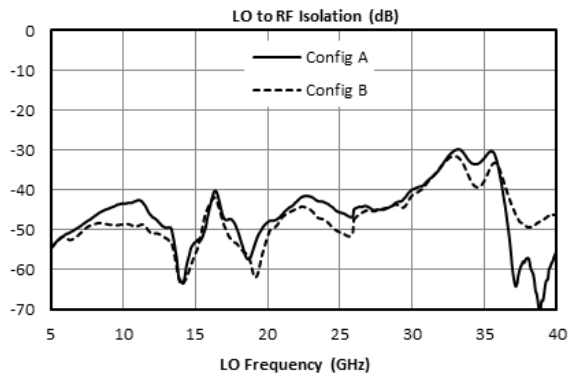
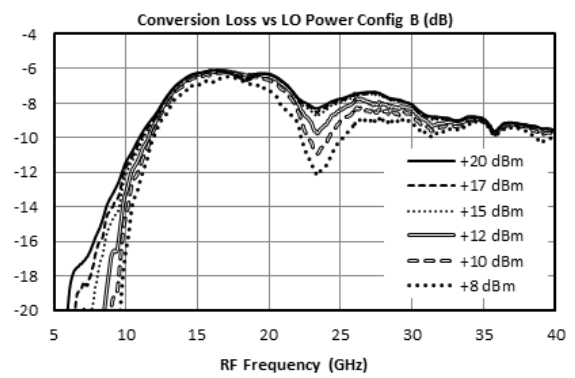
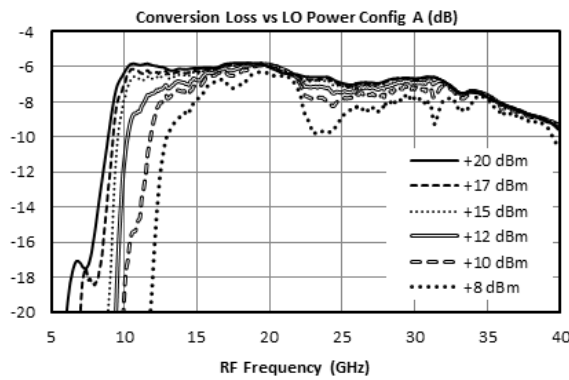
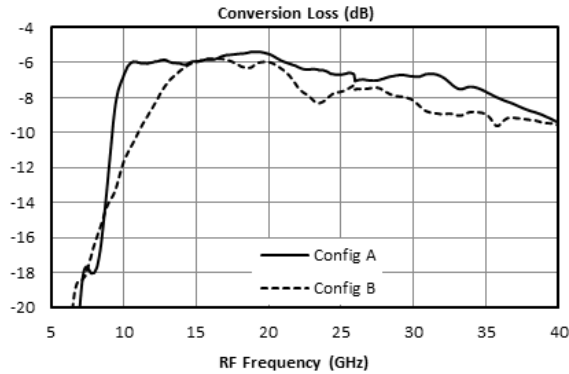
The electrical specifications apply at TA=+25°C in a 50Ω system. Typical data shown is for a down conversion application with a +17 dBm sine wave LO input. Specifications shown for configuration A (B).

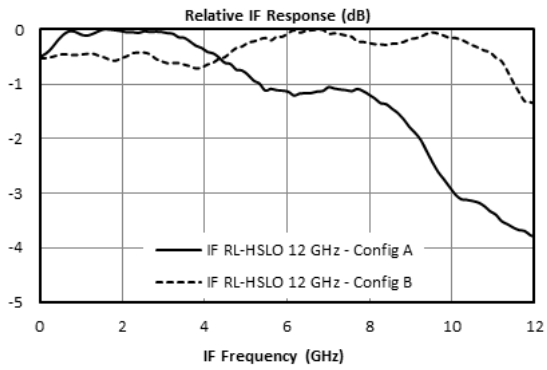
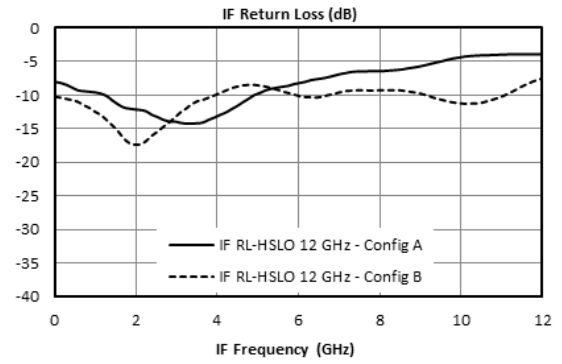
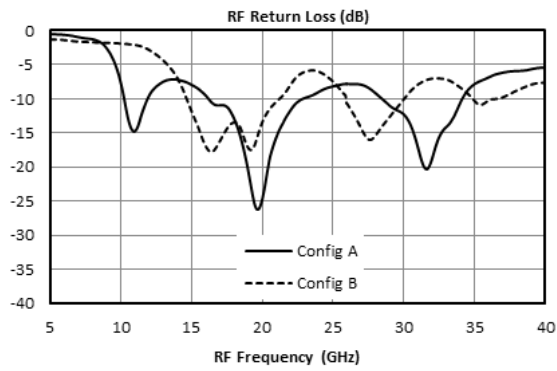
Parameter		Test Conditions	Min	Typical	Max	Units
RF (Pin 8) Frequency Range			10		40	GHz
LO (Pin 2) Frequency Range			10		40	
I (Pin 5) Frequency Range			0		12	
Conversion Loss (CL) ²		RF/LO = 10 - 40 GHz I = DC - 0.2 GHz		7 (8)	12 (14)	dB
		RF/LO = 10 - 40 GHz I = 0.2 - 12 GHz		9 (9)		
Noise Figure (NF) ³		RF/LO = 10 - 40 GHz I = DC - 0.2 GHz		7 (8)		dB
Isolation	LO to RF	RF/LO = 10 - 40 GHz		45 (46)		dB
	LO to IF	IF/LO = 10 - 40 GHz		24 (45)		
	RF to IF	RF/IF = 10 - 40 GHz		45 (23)		
Input IP3 (IIP3)		RF/LO = 10 - 40 GHz I = DC - 0.2 GHz		+20 (+24)		dBm
Input 1 dB Gain Compression Point (P1dB)				+11 (+10)		dBm

² Measured as a down converter to a fixed 91MHz IF.

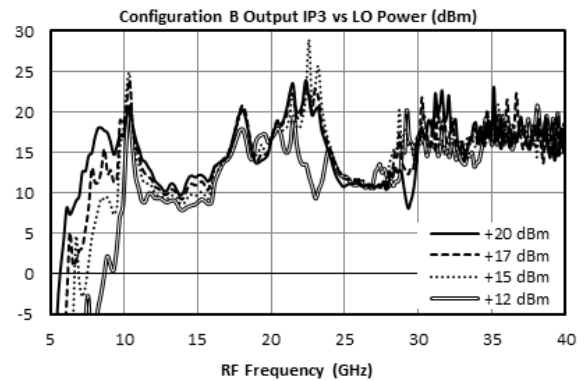
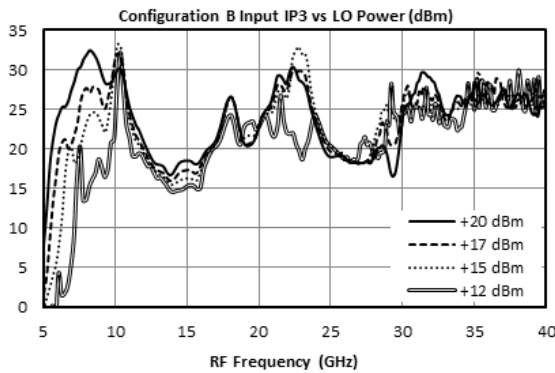
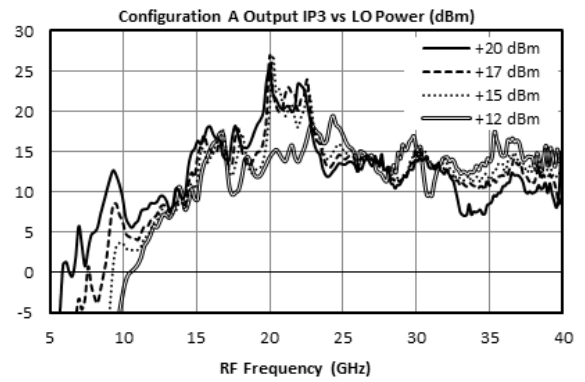
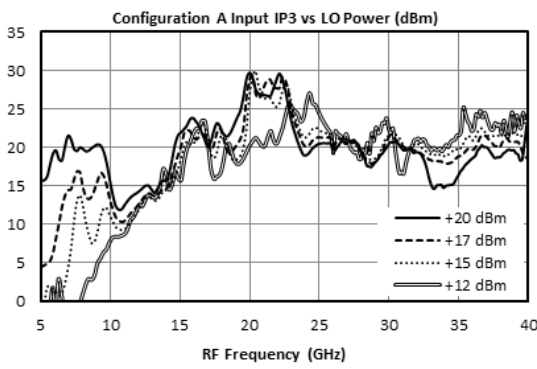
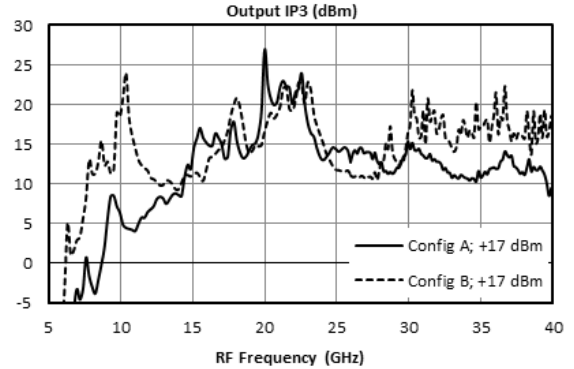
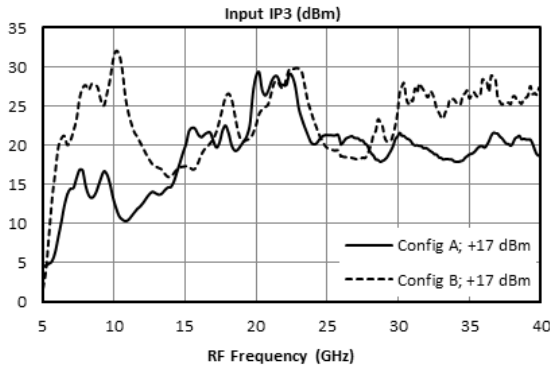
³ Mixer Noise Figure typically measures within 0.5 dB of conversion loss for IF frequencies greater than 5 MHz.

3.6 Typical Performance Plots

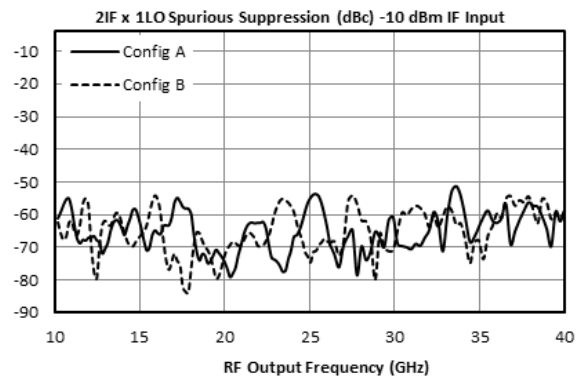
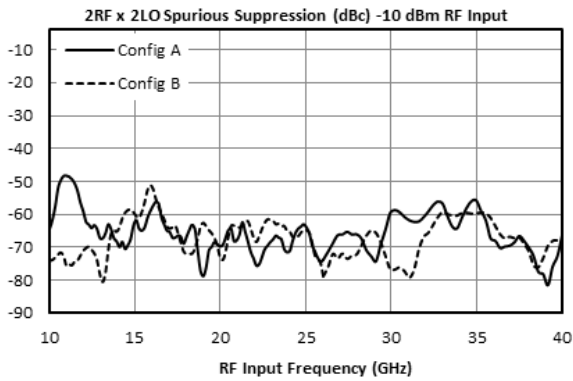
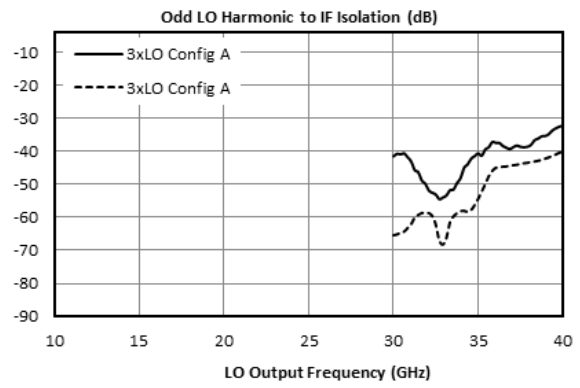
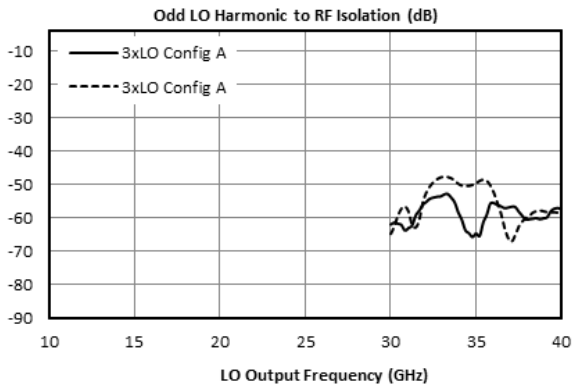
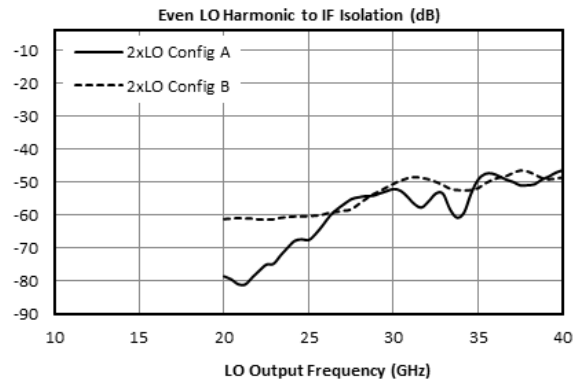
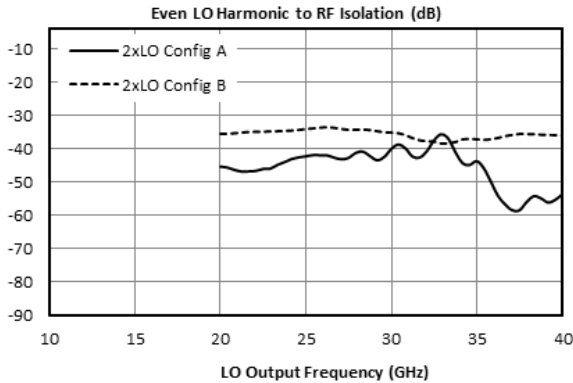




3.6.1 Typical Performance Plots: IP3



3.6.2 Typical Performance Plots: LO Harmonic Isolation



3.6.3 Typical Spurious Performance: Down-Conversion

Typical spurious data is provided by selecting RF and LO frequencies ($\pm m \cdot \text{LO} \pm n \cdot \text{RF}$) within the RF/LO bands, to create a spurious output within the IF band. The mixer is swept across the full spurious band and the mean is calculated. The numbers shown in the table below are for a -10 dBm RF input. Spurious suppression is scaled for different RF power levels by $(n-1)$, where “n” is the RF spur order. For example, the 2RF x 2LO spur is 65 dBc for a -10 dBm input, so a -20 dBm RF input creates a spur that is $(2-1) \times (-10 \text{ dB})$ lower, or 75 dBc. Data is shown for the frequency plan in 3.6 Typical Performance. 0LOx1RF plot is identical to the plot of LO-RF isolation.

Typical Down-conversion spurious suppression (dBc): Config A (B)

-10 dBm RF Input	0xLO	1xLO	2xLO	3xLO	4xLO	5xLO
1xRF	36 (15)	Reference	33 (36)	15 (15)	N/A	N/A
2xRF	75 (75)	64 (60)	65 (67)	63 (59)	65 (68)	59 (60)
3xRF	95 (91)	64 (76)	81 (88)	70 (74)	83 (87)	65 (69)
4xRF	N/A	N/A	107 (109)	107 (105)	109 (112)	114 (107)
5xRF	N/A	N/A	106 (132)	117 (125)	120 (133)	118 (127)

3.6.4 Typical Spurious Performance: Up-Conversion

Typical spurious data is taken by mixing an input within the IF band, with LO frequencies ($\pm m \cdot \text{LO} \pm n \cdot \text{IF}$), to create a spurious output within the RF output band. The mixer is swept across the full spurious output band and the mean is calculated. The numbers shown in the table below are for a -10 dBm IF input. Spurious suppression is scaled for different IF input power levels by $(n-1)$, where “n” is the IF spur order. For example, the 2IFx1LO spur is typically 66 dBc for a -10 dBm input with a sine-wave LO, so a -20 dBm IF input creates a spur that is $(2-1) \times (-10 \text{ dB})$ lower, or 76 dBc. Data is shown for the frequency plan in 3.6 Typical Performance.

Typical Up-conversion spurious suppression (dBc): Config A (B)

-10 dBm IF Input	0xLO	1xLO	2xLO	3xLO	4xLO	5xLO
1xIF	40 (35)	Reference	37 (37)	16 (14)	30 (36)	20 (22)
2xIF	62 (65)	66 (65)	58 (59)	61 (68)	53 (52)	61 (69)
3xIF	88 (90)	72 (68)	75 (78)	58 (68)	71 (77)	57 (67)
4xIF	110 (109)	109 (106)	100 (96)	101 (101)	101 (94)	95 (108)
5xIF	136 (134)	120 (117)	122 (125)	106 (120)	120 (122)	105 (110)

4. Operation

4.1 Ports Operation

IF Port – Used as input on an upconversion, output on downconversion, or LO port in a band shifting application. Signals should be connected by 50 ohm microstrip or coplanar traces to well matched broadband 50 ohm sources and loads. Blocking capacitor is recommended if DC voltage is present on the line.

RF Port – Used as input on a downconversion, output on upconversion, or output in a band shifting application. Signals should be connected by 50 ohm microstrip or coplanar traces to well matched broadband 50 ohm sources and loads.

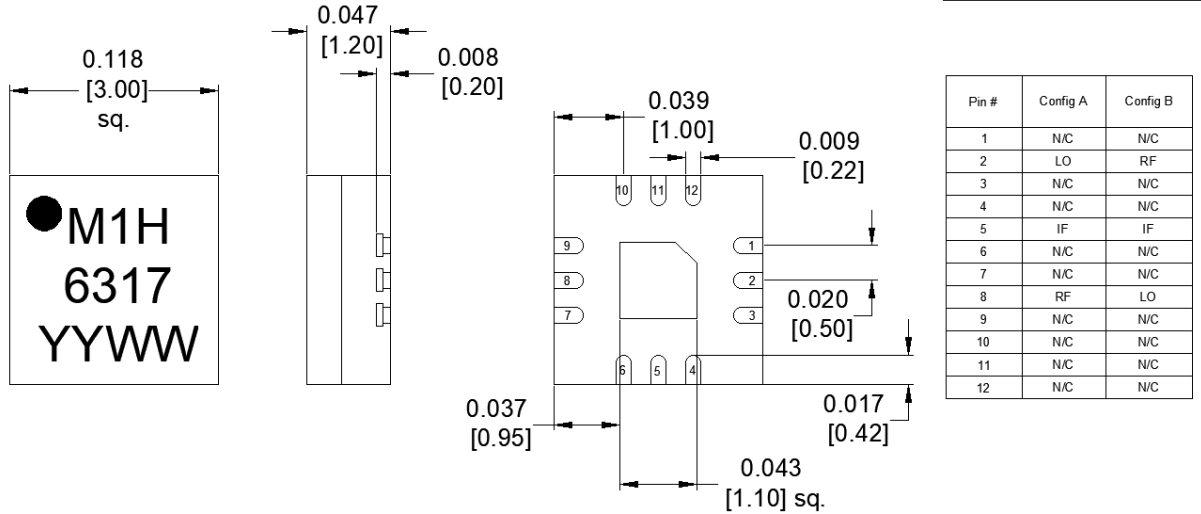
Filtering and Matching- Filtering is generally desired for spurious and image removal on the output port of the mixer. Reflective filters can cause out of band signals to reflect back into the mixer and cause conversion loss ripple, erroneous spurs, and other undesired behaviors. To eliminate these problems it is recommended that the filters be placed as close to the output port as possible. If undesired behavior is still observed, a diplexer with one port terminated or a 1-3 dB attenuator may reduce this problem.

RF Ground – The ground paddle of the QFN should be connected to a low noise RF ground with very low electrical resistance for high frequency operation.

LO Port – The noise floor of the LO input signal should be less than the value of the noise floor plus isolation of the mixer, or a filter is recommended to prevent reduction in dynamic range. An LO amplifier is required if the LO power is below the recommended drive level. It is important to use an amplifier with a broadband 50 ohm match such that it does not reflect spurious signals back into the mixer or other system circuitry.

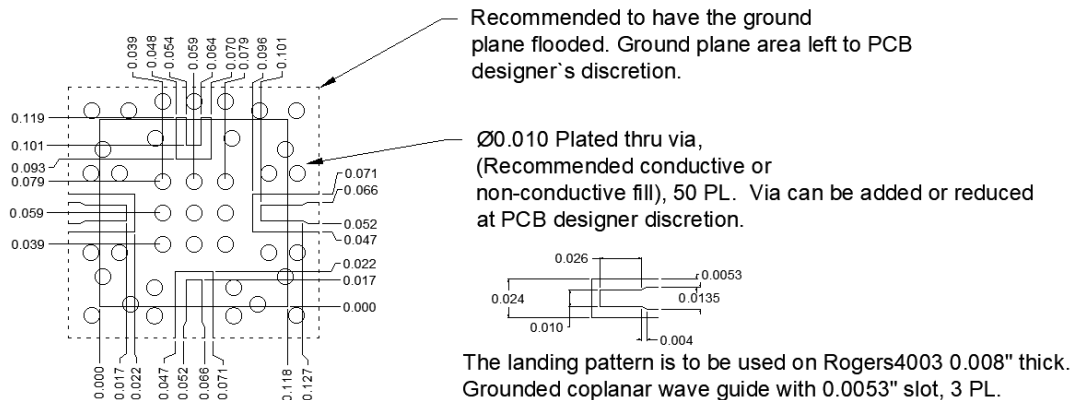
5. Mechanical Data

5.1 PSM Package Outline Drawing



- Substrate material is LCP.
- I/O Leads and Ground Paddle plating is (from base to finish):
 - Ni: 0.5 um MIN
 - Pd: 0.02 um MIN
 - Au 0.05 um MAX
- All unconnected pins should be connected to PCB RF ground.

5.2 PSM Package Footprint

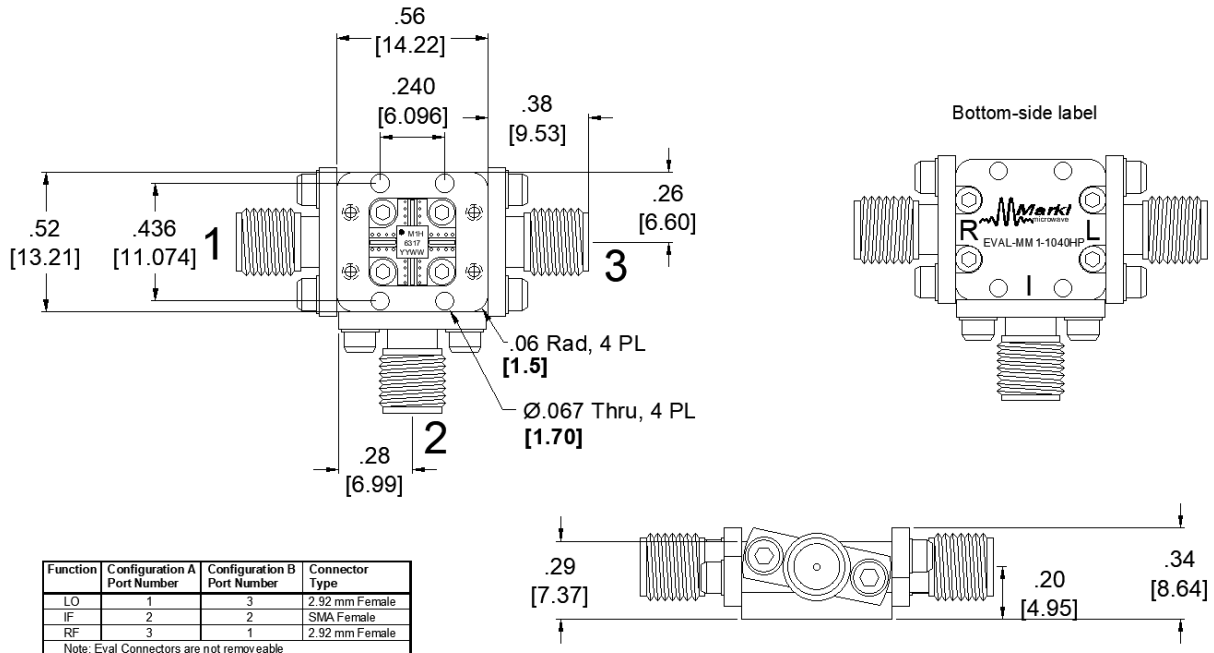


QFN-Package Surface-Mount Landing Pattern

[Click here for a DXF of the above layout.](#)

[Click here for leaded solder reflow.](#) [Click here for lead-free solder reflow.](#)

5.3 Evaluation Board Outline Drawing



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